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DESCRIPTION

The 11th China-Japan Bilateral Symposium on High Temperature Strength of Materials will be held in Chengdu, China, during October 27-31, 2023. The symposium series was initiated in 1992 by the High Temperature Strength and Materials Committee, Materials Institution, Chinese Mechanical Engineering Society and the Committee on High Temperature Strength of Materials, the Society of Materials Science Japan.

The purpose is intended to promote academic and technical exchange between Japanese and Chinese scientists, engineers and to strengthen the technical contacts in the field of high temperature strength of materials between the two nearby countries. More than 100 participants from China and Japan will attend the symposium onsite and share knowledge and findings. A maximum of 15 high-quality papers will be selected for potential publication in Journal of the Mechanical Behavior of Materials for free. Please note that all submitted manuscripts will be peer-reviewed. We believe this special issue can be greatly beneficial for the readers looking into the state of the art on the deformation and fracture of advanced high temperature materials.

A non-exclusive listing of relevant topics includes:

- High Temperature Deformation and Fracture Mechanisms
- ▶ Behavior of Superalloys at High Temperature
- ► Microstructural Study of Heat-Resistant Materials
- Superalloys and Composites for High Temperature Use
- ▶ Deformation and Fracture of Advanced High Temperature Materials Including Intermetallics, Ceramics and Composites etc.

- Creep and Fatigue at High Temperatures
- Creep and Fatigue Interaction
- ► High Temperature Damage Analysis and Design Control
- Defect Assessment and Life Prediction of High Temperature Materials and Components
- ▶ Life Extension of High Temperature Components and Plants

HOW TO SUBMIT

Before submission authors should carefully read the Instructions for Authors.

For an initial submission, the authors are strongly advised to upload their entire manuscript, including tables and figures, as a single PDF file. All submissions to the Special Issue must be made electronically via the Editorial Manager submission and tracking review system: https://www.editorialmanager.com/jmbm

All manuscripts will undergo the standard peer-review process (single blind, at least two independent reviewers). When entering your submission via online submission system please choose the option:

"SI: Deformation and Fracture of Advanced High Temperature Materials"

For more details, please see Authors Statements and Data Sharing Policy documents available in the Supplementary Materials section at the journal website.

The deadline for submissions is May 1st, 2024, but individual papers will be reviewed and published online on an ongoing basis.